
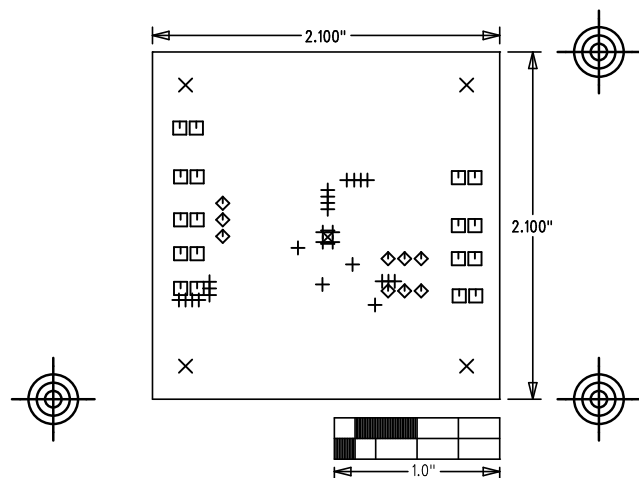


MAX17503A-3.3V OUTPUT EVKIT	
P/N: EPCB17503A	REV A
 maxim integrated™	
LAYER 080609MECS0001	
DATE:	ALL UNITS ARE IN 0.001"

NOTES: UNLESS OTHERWISE SPECIFIED

1. FABRICATE USING PROVIDED GERBER FILES PER LATEST REVISION OF IPC-A-600 UNLESS OTHERWISE NOTED.
2. MATERIAL: RoHS COMPLIANT FR-408 OR SIMILAR LAMINATE MATERIAL WITH $T_g \geq 170$ AND COMPATIBLE WITH LEAD-FREE SOLDERING PROCESS.
3. BOARD DIMENSIONS: 2.10"x2.10" ± 0.010 ".
BOARD THICKNESS: 0.062"
4. LAYERS: 4, SEE LAYER STACK UP
5. MINIMUM TRACE/SPACING: 10MILS/8MILS.
6. COPPER CLAD FINISH: 1oz MINIMUM ON ALL LAYERS.
7. SURFACE MOUNT PADS: 50.
8. SOLDERMASK: GREEN LPI SMOBC.
9. LEGENDS: WHITE, SINGLE-SIDED, NON-CONDUCTIVE EPOXY INK OR EQUIVALENT. CLIPPED ALL LEGENDS FROM EXPOSED METAL.
10. PLATING: MUST BE LEAD FREE AND RoHS COMPLIANT.
11. FINISH: VENDOR SHOULD USE THE MOST ECONOMICAL LEAD FREE AND RoHS COMPLIANT PROCESS AVAILABLE OR AS SPECIFIED IN PURCHASE ORDER.
APPROVED FINISH:
HASL LEAD-FREE
IMMERSION TIN
IMMERSION GOLD
12. VENDOR LOGO & DATE CODE: ALLOWED IN INK ON BOTTOM SIDE ONLY.
13. THRU HOLES: 0.001" MIN.
14. TOLERANCES:
PLATED-THRU HOLES: ± 0.003 "
PATTERN-TO-PATTERN: ± 0.005 "
LEGEND TO LEGEND: ± 0.007 "
SOLDERMASK TO PATTERN: ± 0.005 "



LAYER 1	1.4MIL
PRE-PREG Er=3.8 AS NEEDED	
LAYER 2 SGND	1.4MIL
CORE AS NEEDED Er=3.8	
LAYER 3 SGND	1.4MIL
PRE-PREG Er=3.8 AS NEEDED	
LAYER 4	1.4MIL

ALL DIMENSION IN MIL (0.001 INCH) UNLESS OTHERWISE SPECIFIED.

N/A - NOT AVAILABLE. DO NOT ROUTE TRACES OF THIS TYPE ON THE INDICATE LAYERS.

SIZE	QTY	SYM	PLATED	TOL
0.015	26	+	YES	± 0.003 "
0.125	4	X	YES	± 0.003 "
0.04	18	□	YES	± 0.003 "
0.037	9	◇	YES	± 0.003 "
0.035	1	⊗	YES	± 0.003 "